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Product Change Notification - JAON-04FGES267

Date: 24 Jan 2017

Product Category: Memory

Notification subject: CCB 2746 Final Notice: Qualification of 35.8K process technology for selected products of the 25xx128 and 25xx256 device families available in 8L DFN-S package.

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of 35.8K process technology for selected products of the 25xx128 and 25xx256 device families available in 8L DFN-S package.

Pre Change:

Available in 160K wafer technology fabricated at Microchip fabrication sites FAB2 and FAB4 (Tempe, AZ and Gresham, OR, USA) using 8 inch wafers

Post Change:

Available in 160K wafer technology fabricated at Microchip fabrication sites FAB2 and FAB4 (Tempe, AZ and Gresham, OR, USA) using 8 inch wafers or available in 35.8K wafer technology fabricated at FAB 5 (Colorado Springs, CO, USA) using 6 inch wafers

Pre and Post Change Summary:

	Pre Change	Post Change	
Wafer Technology	160K wafer technology	160K wafer technology	35.8K wafer technology
Fabrication Location	Microchip Fabrication Sites FAB 2 and FAB4 (Tempe, AZ and Gresham, OR, USA)	Microchip Fabrication Sites FAB 2 and FAB4 (Tempe, AZ and Gresham, OR, USA)	FAB 5 (Colorado Springs, CO USA)
Wafer Diameter	8 inches (200 mm)	8 inches (200 mm)	6 inches (150 mm)
Quality certification	ISO/TS16949	ISO/TS16949	ISO9001/TS16949

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying an additional fabrication site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 24, 2017 (date code: 1708)

NOTE:

In order to receive products only fabricated with the current 160K process please use the revised part number identified with RVA added to the end of the part number (see example below).

Standard Part Number: 25xx128x-x/xx or 25xx256x-x/xx

Revised Part Number (160K only): 25xx128x-x/xxRVA or 25xx256x-xx/xxRVA

Time Table Summary:

	December 2016					January 2017				February 2017			
	48	49	50	51	52	01	02	03	04	05	06	07	08
Workweek													
Initial PCN Issue Date		X											
Qual Report Availability									X				
Final PCN Issue Date									X				
Estimated Implementation Date													X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

December 7, 2016: Issued initial notification.

January 24, 2017: Issued final notification. Attached the qualification report. Provide estimated first ship date to be on February 24, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_JAON-04FGES267_Qual Report.pdf](#)
- [PCN_JAON-04FGES267_Affected CPN.pdf](#)
- [PCN_JAON-04FGES267_Affected CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-04FGES267
CATALOG_PART_NBR
25AA256-I/MF
25AA256T-I/MF
25LC256-E/MF
25LC256-I/MF
25LC256T-E/MF
25LC256T-I/MF
25AA128-I/MF
25AA128T-I/MF
25LC128-E/MF
25LC128-I/MF
25LC128T-E/MF
25LC128T-I/MF